

Fig. 1

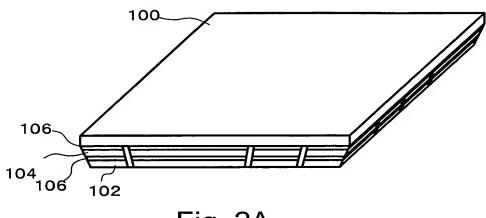


Fig. 2A

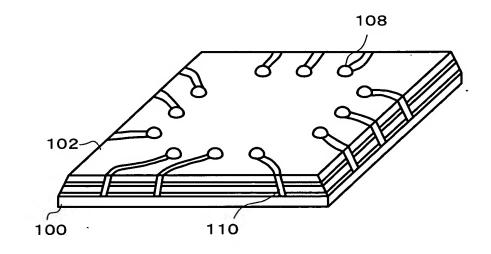


Fig. 2B

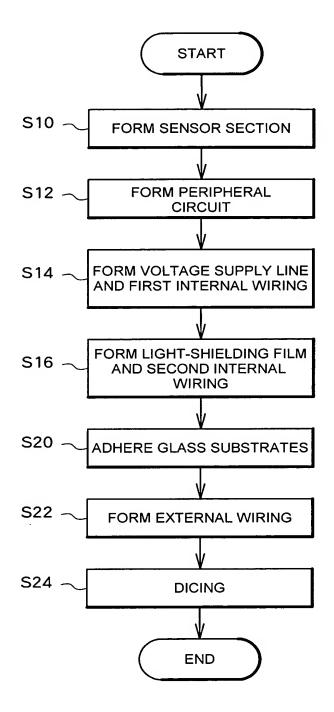
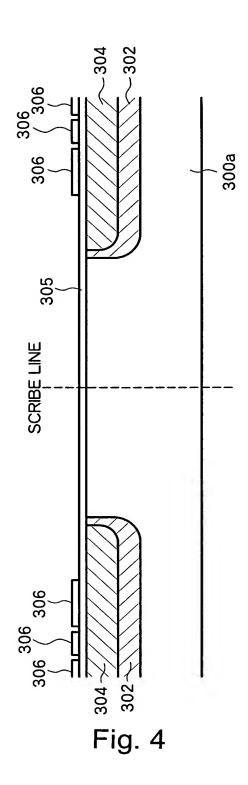
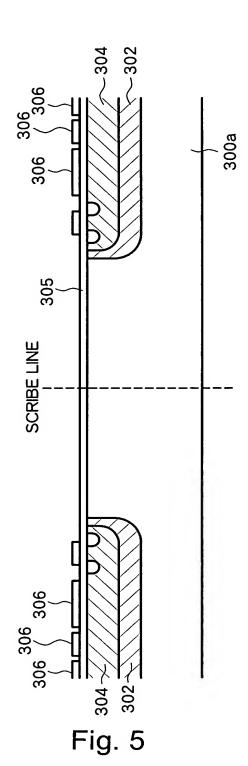


Fig. 3

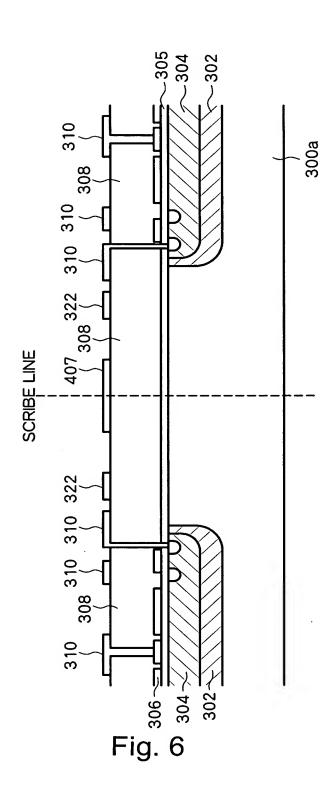
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Yoshihiro OKADA, et al.
Semiconductor Integrated Device Having
Solid-State Image Sensor Packaged Within
And Production Method For Same,
Express Mail Label EV 667 738 681 US
11 Sheets of Drawings; Sheet 4 of 11



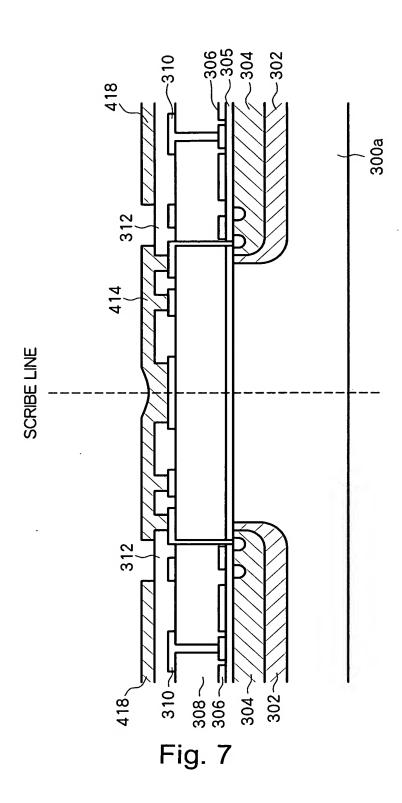
4/11



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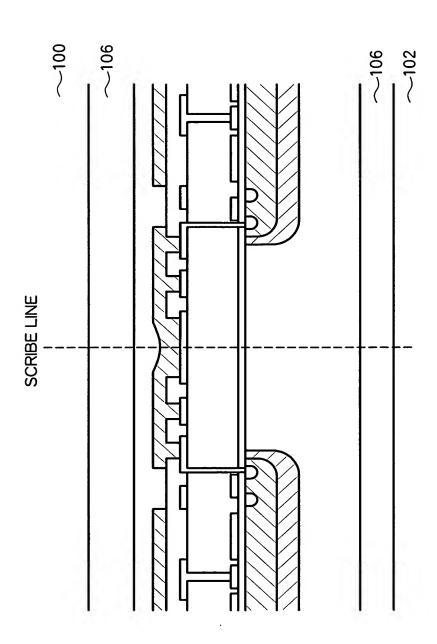


Fig. 8

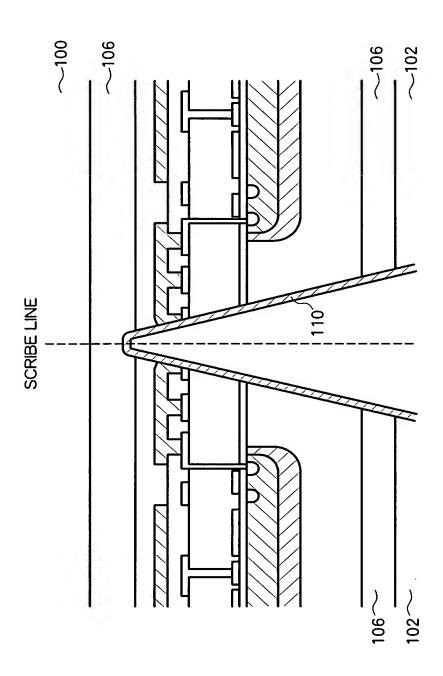


Fig. 9

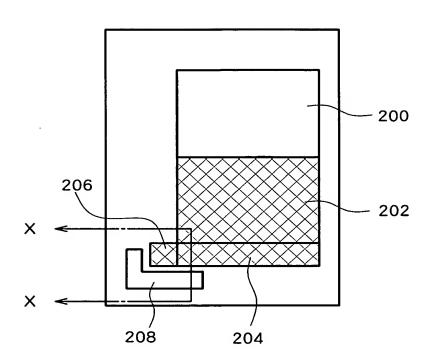


Fig. 10

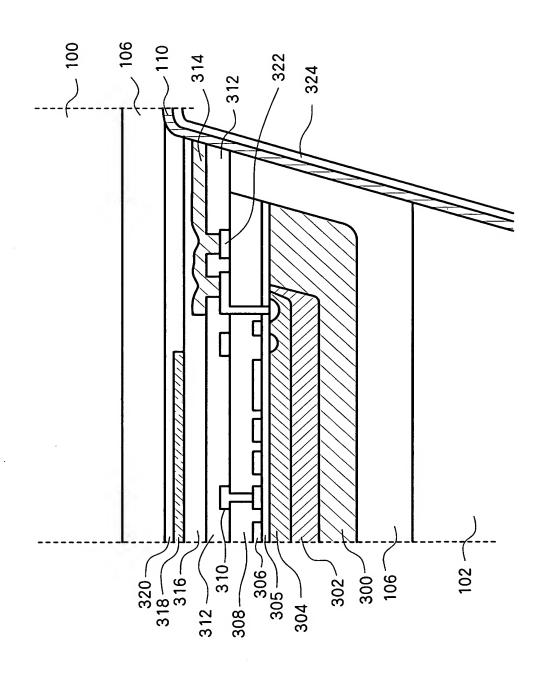


Fig. 11